




Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
SM6T6V8CA	HHZI*TWBV68D	A	ZA41	2019-01-28
	Amount	UoM	Unit type	ST ECOPACK Grade
	107	mg	Each	ECOPACK2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant ( in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SOJ	3X3X0.9	2	J bend	
Comment	Package: SMB CLIP (SOD 6 NEW)			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : ELV directive : 2000/53/EC amended 2017/2096 _November 2017	
Query	Response
1 - Product(s) meets EU ELV requirements without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
Exemption Id.	Description
8e	Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)

QueryList : California Prop65 list, dated 26th October 2018			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.02	Die	159
Lead	3.34	Soft solder	31187

QueryList : REACH-15th January 2019				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
Lead	1000 ppm	3.34	Soft solder	31187
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material
Lead	1000 ppm	3.34	Soft solder	924889

Material Composition Declaration :						Mfr Item Name	HHZJ*TWBV68D					
note : Substance present with less 0.001mg will not be declared in this document												
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	1.623	mg	supplier	die	Silicon (Si)	7440-21-3		1.573	mg	969193	14701
				supplier	metallization	Aluminium (Al)	7429-90-5		0.009	mg	5545	84
				supplier	metallization	Gold (Au)	7440-57-5		0.007	mg	4313	65
				supplier	passivation	Nickel (Ni)	7440-02-0		0.007	mg	4313	65
				supplier	Passivation	Silicon Oxide	7631-86-9		0.009	mg	5545	84
				supplier	back side metallization	Aluminium (Al)	7429-90-5		0.006	mg	3697	56
				supplier	back side metallization	Gold (Au)	7440-57-5		0.002	mg	1233	20
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.010	mg	6161	93
				Leadframe & Clip	Copper and its alloy	42.837	mg	supplier	alloy	Copper (Cu)	7440-50-8	
supplier	alloy	Zinc (Zn)	7440-66-6						0.002	mg	47	19
supplier	alloy	Iron (Fe)	7439-89-6						0.004	mg	93	37
supplier	alloy	Phosphorus (P)	12185-10-3						0.015	mg	350	140
supplier	soft solder	Silver (Ag)	7440-22-4						0.090	mg	24945	841
Die attach	Other organic material	3.608	mg	supplier	soft solder	Tin (Sn)	7440-31-5		0.181	mg	50166	1692
				supplier	soft solder	Lead (Pb)	7439-92-1	7a-Lead in high me	3.337	mg	924889	31187
				supplier	mold compound	silica fused	7631-86-9		42.205	mg	739997	394439
Encapsulation	Other organic material	57.034	mg	supplier	mold compound	silica quartz	14808-60-7		11.405	mg	199968	106589
				supplier	mold compound	phenolic resin	9003-35-4		2.853	mg	50023	26664
				supplier	mold compound	carbon black	1333-86-4		0.571	mg	10012	5336
Connection coating	Other inorganic material	1.898	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		1.898	mg	1000000	17738